

February 11

**Assistant Commissioner of Patents** To: Office of Initial Patent Examination

**Customer Service Center** Washington, D.C. 20231

From: Stephen B. Ackerman

Subject:

Serial No.:

10/042,074

Filing Date: 01/08/02

Inventor:

D. N. Yaung, et al.

Title:

Grid Metal Design for Large Density CMOS Image Sensor

## REQUEST TO CORRECT FILING RECEIPT

Dear Sir:

On the copy of the enclosed Filing Receipt, there are errors in the list of Applicants. The Applicants' residences are incorrect. Following is a list of the Applicants' names and their corrected residences:

Dun-Nian Yaung, Taipei, Taiwan Shou-Gwo Wuu, Hsin-Chu City, Taiwan Chien-Hsien Tseng, Hsin-Chu, Taiwan.

Please make the necessary changes to correct the errors on the Filing Receipt. A copy of the filed Declaration is enclosed for clarification.

If there are any questions, please contact the undersigned attorney at (845) 452-5863. Thank you for your attention to this matter.

Respectfully Submitted,

Stephen B. Ackerman, Reg. No. 37,761





## United States Patent and Trademark Office

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APPLICATION NUMBER **FILING DATE** GRP ART UNIT FIL FEE REC'D ATTY.DOCKET.NO DRAWINGS TOT CLAIMS IND CLAIMS 10/042,074 01/08/2002 2825 1352 TS01-450 3 40 6

**CONFIRMATION NO. 3909** 

STEPHEN B. ACKERMAN 20 MCINTOSH DRIVE POUGHKEEPSIE, NY 12603



FILING RECEIPT
\*OC000000007408846\*

Date Mailed: 02/01/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

Dun-Nian Yaung, Taipei, CHINA; Shou-Gwo Wuu, Hsin-Chu City, CHINA; Chien-Hsien Tseng, Hsinchu, CHINA;

## **Assignment For Published Patent Application**

Taiwan Semiconductor Manufacturing Company;

Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted 02/01/2002

Projected Publication Date: Request for Non-Publication Acknowledged

Non-Publication Request: Yes

Early Publication Request: No

Title

Grid metal design for large density CMOS image sensor

**Preliminary Class** 

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